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**Aehr Test Systems Receives Follow-on Production Order  
for its FOX-XP™ Test and Burn-in System**

**Fremont, CA (April 4, 2017) – Aehr Test Systems (NASDAQ: AEHR)**, a worldwide supplier of semiconductor test and burn-in equipment, today announced that it has received a \$3.7 million follow-on order from a subcontractor to its lead customer for the FOX-XP Test and Burn-in System. The order is for a second production FOX-XP test and burn-in system configured with Aehr Test's new highly parallel singulated die / module test interface technology, and includes a FOX-XP system and set of proprietary DiePak® carriers. This system is expected to ship in Aehr Test's fiscal first quarter ending August 31, 2017.

Aehr Test completed shipment of the initial FOX-XP system configuration previously ordered by this customer and received customer acceptance after the close of its fiscal third quarter. That configuration was part of an order in excess of \$4 million that included a full production FOX-XP test cell with a set of proprietary DiePak Carriers and a DiePak Autoloader.

Gayn Erickson, President and CEO of Aehr Test Systems, commented, "With acceptance of the initial FOX-XP system configuration and DiePak Carrier delivered to this customer within just the last month, we are excited to already receive this follow-on order for a second FOX-XP system. This system is a high power configuration with nine individual Blades for testing singulated die / modules with our proprietary DiePak carriers. We continue to work closely with the end customer of this application, which represents our second major customer for the FOX-XP Test and Burn-in System."

Aehr Test's new FOX-XP system configuration is capable of testing and burning-in devices to meet the critical quality and reliability needs of its customers in singulated die or module level and adds to the full wafer test capabilities of this platform. This high power configuration is available with up to nine individual Blades that can each test up to 1,024 devices using Aehr Test's proprietary DiePak Carriers. Each DiePak Carrier can handle device power loads of up to 2,000 Watts of power, which provides a higher level of parallelism and power management for these types of devices than is available from any other supplier in the market. Aehr Test's production WaferPak™ Contactors and DiePak Carriers utilize proprietary technology for contacting thousands of tiny devices in wafer, singulated die, module, or system level / module form.

## **About Aehr Test Systems**

Headquartered in Fremont, California, Aehr Test Systems is a worldwide provider of test systems for burning-in and testing logic, optical and memory integrated circuits and has an installed base of more than 2,500 systems worldwide. Increased quality and reliability needs of the Automotive and Mobility integrated circuit markets are driving additional test requirements, incremental capacity needs, and new opportunities for Aehr Test products in package, wafer level, and singulated die/module level test. Aehr Test has developed and introduced several innovative products, including the ABTS™ and FOX-P families of test and burn-in systems and FOX WaferPak Aligner, FOX-XP WaferPak Contactor, and FOX DiePak® Carrier. The ABTS system is used in production and qualification testing of packaged parts for lower power and higher power logic devices as well as all common types of memory devices. The FOX-XP system is a full wafer contact and singulated die/module test and burn-in system used for burn-in and functional test of complex devices, such as leading-edge memories, digital signal processors, microprocessors, microcontrollers, systems-on-a-chip, and integrated optical devices. The WaferPak contactor contains a unique full wafer probe card capable of testing wafers up to 300mm that enables IC manufacturers to perform test and burn-in of full wafers on Aehr Test FOX systems. The DiePak Carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of both bare die and modules. For more information, please visit Aehr Test System's website at [www.aehr.com](http://www.aehr.com).

## **Safe Harbor Statement**

This press release contains certain forward-looking statements based on current expectations, forecasts and assumptions that involve risks and uncertainties. These statements are based on information available to Aehr Test as of the date hereof and actual results could differ materially from those stated or implied due to risks and uncertainties. Forward-looking statements include statements regarding Aehr Test's expectations, beliefs, intentions or strategies regarding the FOX products, including statements regarding future market opportunities and conditions, expected product shipment dates and customer orders or commitments. These risks and uncertainties include, without limitation, acceptance by customers of the FOX and DiePak Carrier technologies, acceptance by customers of the FOX-XP system, DiePak Autoloader and DiePak Carriers shipped upon receipt of a purchase order and the ability of new products to meet customer needs or perform as described, as well as general market conditions, customer demand and acceptance of Aehr Test's products and Aehr Test's ability to execute on its business strategy. See Aehr Test's recent 10-K, 10-Q and other reports filed from time to time with the Securities and Exchange Commission for a more detailed description of the risks facing Aehr Test's business. Aehr Test disclaims any obligation to update information contained in any forward-looking statement to reflect events or circumstances occurring after the date of this press release.

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